



SDLink datasheet

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This document describes SDLink specification.

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1.DC Electrical Characteristic

[Table1-1] Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Unit
Vcc1	Supply voltage for microSD	-0.5	+4.3	V
Vcc2	Supply voltage for Configuration	-0.5	+4.3	V
Tstg	Storage temperature	-40	+85	О°
Topr	Operating temperature	-20	+85	О°
Vin	DC input voltage	-2.0	+4.3	V
lout	DC output voltage	-25	+25	mA

[Table1-2] Recommended Operating Condition

Symbol	Parameter	Min	Max	Unit
Vcc1	Supply voltage for microSD	+3.0	+3.6	V
Vcc2	Supply voltage for Configuration (3.3V)	+3.0	+3.6	V
	Supply voltage for Configuration (3.0V) (*1)	+2.85	+3.15	
	Supply voltage for Configuration (2.5V)	+2.375	+2.625	V
	Supply voltage for Configuration (1.8V)	+1.7	+1.9	V
Topr	Operating temperature	0	+70	О°
Vih	High level input voltage (Vcc2=3.3V)	+1.7	+3.6	V
	High level input voltage (Vcc2=3.0V) (*1)	+1.7	+3.15	V
	High level input voltage (Vcc2=2.5V)	+1.7	+2.625	V
	High level input voltage (Vcc2=1.8V)	+1.25	+1.9	V
Vil	Low level input voltage (Vcc2=3.3V)	-0.5	+0.8	V
	Low level input voltage (Vcc2=3.0V) ^(*1)	-0.3	+0.8	V
	Low level input voltage (Vcc2=2.5V)	-0.5	+0.7	V
	Low level input voltage (Vcc2=1.8V)	-0.5	+0.7	V
Voh	High level output voltage (Vcc2=3.3V)	+2.4		V
	High level output voltage (Vcc2=3.0V) ^(*1)	+2.4		V
	High level output voltage (Vcc2=2.5V)	+2.0		V
	High level output voltage (Vcc2=1.8V)	+1.35		V
Vol	Low level output voltage (Vcc2=3.3V)		+0.45	V
	Low level output voltage (Vcc2=3.0V) (*1)		+0.45	V
	Low level output voltage (Vcc2=2.5V)		+0.45	V
	Low level output voltage (Vcc2=1.8V)		+0.45	V

Note:

(*1) Vcc2=3.0V Configuration is valid only for Stratix4.



2.SDLink Module Outline

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[Figure 2-1] SDLink Module Outline

- Connection Pins for user board connection are DIP type pins of two lines.
- 10 pins of pin number A, B, C, 1to5, D, and E are [CON2] side, and 10 pins of pin number F, G, 6to10, H, J, and K are [CON3] side.
- Pin number 1 at [CON2] side has white circle overlay indicator.
- For FlashLink-compatible version (SL001-FL), [CON2] only mounts pin number 1to5 and [CON3] only mounts pin number 6to10, so total pin count is 10.
- Because microSD card is push-lock type socket, prepare enough space at open side of the socket for microSD card insertion and extraction.
- Bi-color LED shows FPGA configuration status.





3. Mechanical Data



- SDLink module size is Length=28mm, Width=22.86mm, Height=12.2mm.
- When module is directly soldered on the user board, module height is about 8.5mm from the user board surface.
- Connection pin gap is 20.32mm (800mil), and pin pitch is 2.54mm (100mil).
- For FlashLink-compatible version (SL001-FL), pin number A, B, C, D, E, F, G, H, J, and K are not mounted.



4.User Board Recommendation Pattern



[Figure 4-1] User board recommendation pattern

- Keep part mount limitation area shown in Figure4-1 on the user board.
- Gray area of Limitation area #1 specifies SDLink module mount area, and slanted area of Limitation area #2 specifies necessary space to insert/extract microSD card.
- Do not mount part on the Limitation area #1 (Pattern routing is possible).
- On the Limitation area#2, mount part height should be 3mm or less.



5.Connection Diagram and Pin Description



- [Figure5-1] User board connection diagram
- Refer to [SDLink User Board Design Guide] (Document number: SL-AN01) for the practical circuit design.





[Table5-1] Connection Pin description (CON2)

#	Signal Name	I/O	Polarity	Description
Α	GND	Power	-	Signal Ground
В	DATA1 /DIN1	Out	Positive	 Configuration data bit #1
С	DATA2 /DIN2	Out	Positive	Configuration data bit #2
1	DCLK1 /CCLK1	Out	Positive	 Configuration clock #1 This pin and DCLK2/CCLK2 are the identical clock output. To keep clock signal quality, balance both clock fan out count. Mount Thevenin termination network that resistor value is about 330 to 1Kohm for both clock pattern traces. Build single stroke pattern starting from SDLink and end at termination resistor for clock signal.
2	CONF_DONE /DONE	In	Positive	 Configuration completion status Mount 1K to 10Kohm pull-up resistor toward the configuration power supply on the user board. This pin is 3.3V tolerant whichever VIO voltage is 1.8V, 2.5V, or 3.3V.
3	nCONFIG /nPROG	Out	Negative	 Configuration start signal Mount 1K to 10Kohm pull-up resistor toward the configuration power supply on the user board because it is open-drain output. SDLink will execute re-configuration when forced to low level on the user board. This pin is 3.3V tolerant whichever VIO voltage is 1.8V, 2.5V, or 3.3V.
4	nSTATUS /nINIT	In	Negative	 Configuration error status Mount 1K to 10Kohm pull-up resistor toward the configuration power supply on the user board. This pin is 3.3V tolerant whichever VIO voltage is 1.8V, 2.5V, or 3.3V.
5	DATA0 /DIN0	Out	Positive	Configuration data bit #0
D	DATA3 /DIN3	Out	Positive	 Configuration data bit #3
Е	GND	Power	-	Signal Ground





[Table 5-2] Connection Pin description (CON3)

#	Signal Name	I/O	Polarity	Description
F	DATA4 /DIN4	Out	Positive	Configuration data bit #4
G	DATA5 /DIN5	Out	Positive	Configuration data bit #5
6	GND	Power	-	Signal Ground
7	DCLK2 /CCLK2	Out	Positive	 Configuration clock #2 This pin and DCLK1/CCLK1 are the identical clock output. To keep clock signal quality, balance both clock fan out count. Mount Thevenin termination network that resistor value is about 330 to 1Kohm for both clock pattern traces. Build single stroke pattern starting from SDLink and end at termination resistor for clock signal.
8	GND	Power	-	Signal Ground
9	+3.3V	Power	-	 +3.3V power supply for microSD User board must supply +3.3V Mount bypass capacitor that capacity is 0.1uF or larger adjacent to this pin on the user board.
10	GND	Power	-	Signal Ground
Н	DATA6 /DIN6	Out	Positive	 Configuration data bit #6
J	VIO	Power	-	 Configuration power supply Supply either of +3.3V (+3.0V for Stratix4), +2.5V, or +1.8V to adjust to the configuration power supply of FPGA. Fundamentally, adjust this VIO voltage to the IO Bank voltage of configuration clock input in FPGA. Mount bypass capacitor that capacity is 0.1uF or larger adjacent to this pin on the user board.
K	DATA7 /DIN7	Out	Positive	Configuration data bit #7

• For FlashLink-compatible version (SL001-FL), pin number A, B, C, D, E, F, G, H, J, and K are not mounted. And 3.3V configuration power is supplied via Pin#9.





6.Timing Chart



[Figure6-1] Timing Chart

[Table6-1] Timing characteristics

Symbol	Description	Min	Тур	Max	Unit
tPLS	nCONFIG/nPROG low pulse width		8		ms
tSDI	microSD initialization duration		300		ms
	(It depends on microSD brand and type)				
tWAI	Variable delay set by SDLink software	0	0	2550	ms
tDLY	nSTATUS/nINIT high release to 1 st data output delay		250		ms
tSU	Configuration data setup time		12.5		ns
tH	Configuration data hold time		12.5		ns
tCYC	Configuration clock cycle time	400	50	25	ns
сус	DCLK/CCLK additional clock cycle count after		256	512	(count)
	configuration completion.				

Note:

- Timing Characteristics are tentative and might be changed without notice
- Typical condition: configuration in 1-bit Passive Serial mode, normal microSD Card, and highest configuration speed.
- tPLS : nCONFIG/nPROG is driven low by internal controller of SDLink. For power-up configuration, real tPLS duration will be extended to very long time (several hundred milli-sec) because of additional initialization period of SDLink internal controller and microSD.
- tDLY: Real tDLY duration will vary with FPGA size or microSD initialization time on the SDLink.